

IN THE CLAIMS:

Please cancel claims 1 through 67 and substitute therefore the following claims:

68. An electro-chemical deposition system, comprising:

- a) a wafer transfer apparatus;
- b) a loading station disposed in connection with the wafer transfer apparatus;
- c) one or more processing cells disposed in connection with the wafer transfer apparatus;
- d) an electrolyte supply fluidly connected to the one or more processing cells;
- e) a wafer cleaner station disposed in connection with the wafer transfer apparatus;
- and
- f) a thermal anneal chamber disposed in connection with the wafer transfer apparatus.

69. The system of claim 68, wherein the wafer cleaner is a rinse-dry chamber.

70. A system for depositing a layer on a substrate, comprising:

- at least one electrolyte processing cell;
- at least one annealing chamber;
- at least one substrate cleaner; and
- a substrate transfer apparatus adapted to access the electrolyte processing cell, the annealing chamber, and the substrate cleaner.

71. The system of claim 70, wherein the substrate cleaner is a rinse/dry chamber.

72. The system of claim 70, wherein the substrate transfer apparatus comprises a first robot positioned to access the substrate cleaner and the electrolyte processing cell, and a second robot positioned to access the substrate cleaner and the annealing chamber.

73. An electro-chemical deposition system, comprising:

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- a) a mainframe having a mainframe wafer transfer robot;
  - b) a loading station disposed in connection with the mainframe;
  - c) one or more processing cells disposed in connection with the mainframe;
  - d) an electrolyte supply fluidly connected to the one or more processing cells;
  - e) a rinse-dry (RD) chamber disposed for access to the loading station; and
  - f) a thermal anneal chamber disposed for access to the loading station.

74. The system of claim 73 wherein the thermal anneal chamber comprises a rapid thermal anneal chamber having a heater plate.

75. The system of claim 74 wherein the heater plate comprises an atmospheric pressure heater plate.

76. The system of claim 73, further comprising:

- e) a system controller adapted to control operations of one or more components of the electro-chemical deposition system.

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77. The system of claim 76, wherein the thermal anneal chamber further comprises a gas inlet adapted to introduce one or more gases into the thermal anneal chamber.

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